

39 Top High Tech presentations at the upcoming World Congress on Active & Intelligent Packaging in Amsterdam.

You will discover all about Packaging Nano technologies, Tags and Indicators, Consumer Engagement, Software and Cloud developments, Brand Protection, Printed Electronics, Augmented Reality, Packaging as your Media Channel and of course high tech solutions to fight Food Waste.

If you want to be part of the most advanced community in packaging, have a look at the speaker list and register very soon: [SPEAKER LIST HERE](#)

You will meet all the major packaging companies from all over the world as well as brands as Nestlé, Abbott, Strauss Group, Apple, Absolut, Danone, Unilever and we are working on a great A&IP Challenge with PepsiCo.

Stay ahead in packaging. Do not stay at home.

Kind regards,

Eef de Ferrante

Managing Director AIPIA